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30V N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(ON)} Max	I _D Max T _A = +25°C
201/	15mΩ @ V _{GS} = 10V	9.3A
30V	20mΩ @ V _{GS} = 4.5V	8.1A

Features

- 0.6mm Profile Ideal for Low Profile Applications
- PCB Footprint of 4mm²
- Low Gate Threshold Voltage
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Description

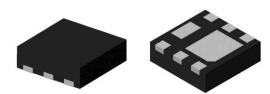
This MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}), yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Battery Management Application
- Power Management Functions
- DC-DC Converters

Mechanical Data

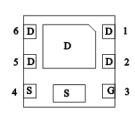
- Case: U-DFN2020-6 (Type F)
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @4
- Weight: 0.007 grams (Approximate)

U-DFN2020-6 (Type F)

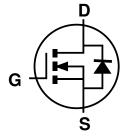


Top View

Bottom View



Pin Out Bottom View



Internal Schematic

Ordering Information (Note 4)

Part Number	Case	Packaging
DMN3021LFDF-7	U-DFN2020-6 (Type F)	3,000/Tape & Reel
DMN3021LFDF-13	U-DFN2020-6 (Type F)	10,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



F2 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: D = 2016) M = Month (ex: 9 = September)

Date Code Key

Year	2016		2017	2018		2019	2020		2021	2022	!	2023
Code	D		Е	F		G	Н			J		K
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings $(@T_A = +25^{\circ}C, \text{ unless otherwise specified.})$

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage	V_{DSS}	30	V		
Gate-Source Voltage	V_{GSS}	±20	V		
Continuous Drain Current (Note 6) V 10V	Steady State	$T_A = +25$ °C $T_A = +70$ °C	I _D	9.3 7.5	А
Continuous Drain Current (Note 6) V _{GS} = 10V	t<5s	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I _D	11.8 9.4	А
Pulsed Drain Current (380µs Pulse, Duty Cycle = 1%	I_{DM}	50	Α		
Maximum Continuous Drain-Source Diode Forward (Is	1.8	Α		
Avalanche Current (Note 7) L = 0.1mH	I _{AS}	18	Α		
Repetitive Avalanche Energy (Note 7) $L = 0.1 \text{mH}$	Eas	16	mJ		

Thermal Characteristics

Characteristic	Symbol	Value	Unit		
Total Bower Dissipation (Note 5)	$T_A = +25$ °C	В	0.73	W	
Total Power Dissipation (Note 5)	$T_A = +70$ °C	P_{D}	0.47		
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	D	174	°C/W	
memial nesistance, Junction to Ambient (Note 5)	t < 5s	$R_{\Theta JA}$	112	C/VV	
Total Power Dissipation (Note 6)	$T_A = +25$ °C	P _D	2.03	W	
Total Power Dissipation (Note 6)	$T_A = +70^{\circ}C$	PD	1.30		
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	Steady State			
memial nesistance, Junction to Ambient (Note 6)	t < 5s	$R_{\Theta JA}$	40	°C/W	
Thermal Resistance, Junction to Case (Note 6)	$R_{\Theta JC}$	13			
Operating and Storage Temperature Range		T _{J,} T _{STG}	-55 to +150	°C	

Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)			71				
Drain-Source Breakdown Voltage	BV _{DSS}	30	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	_	_	1	μΑ	$V_{DS} = 30V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)				•		·	
Gate Threshold Voltage	V _{GS(TH)}	1.0	_	2.2	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
Static Drain-Source On-Resistance			_	15	mΩ	$V_{GS} = 10V, I_D = 7A$	
Static Diain-Source On-nesistance	R _{DS(ON)}	_	_	20	11177	$V_{GS} = 4.5V, I_D = 7A$	
Diode Forward Voltage	V _{SD}	_	0.8	1.2	V	V _{GS} = 0V, I _S = 2.2A	
DYNAMIC CHARACTERISTICS (Note 9)				•		·	
Input Capacitance	C _{ISS}	_	706	_		V _{DS} = 15V, V _{GS} = 0V, f = 1.0MHz	
Output Capacitance	Coss	_	112	_	pF		
Reverse Transfer Capacitance	C _{RSS}	_	81	_		I = I.UVIDZ	
Gate Resistance	R _G	_	2.6	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge (V _{GS} = 10V)	Q _G	_	14	_			
Total Gate Charge (V _{GS} = 4.5V)	Q _G	_	6.7	_		., .=., . =.	
Gate-Source Charge	Q _{GS}	_	1.9	_	nC	$V_{DS} = 15V, I_D = 5A$	
Gate-Drain Charge	Q_{GD}	_	2.5	_			
Turn-On Delay Time	t _{D(ON)}	_	5.4	_			
Turn-On Rise Time	t _R	_	6.8	_		$V_{DS} = 15V, V_{GS} = 4.5V,$	
Turn-Off Delay Time	t _{D(OFF)}	_	9.7	_	ns	$R_G = 1.7\Omega$, $I_D = 5A$	
Turn-Off Fall Time	te	_	4.7	_			

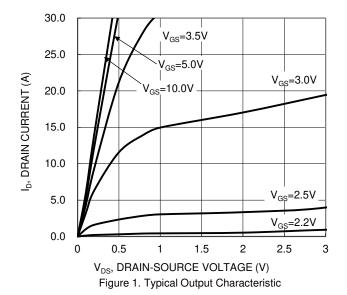
Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
 Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate.

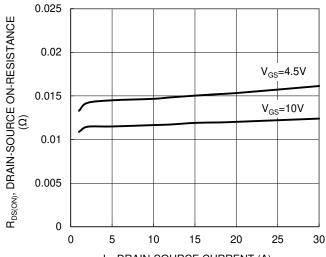
^{7.} I_{AS} and E_{AS} rating are based on low frequency and duty cycles to keep $T_J = +25$ °C.

^{8.} Short duration pulse test used to minimize self-heating effect.

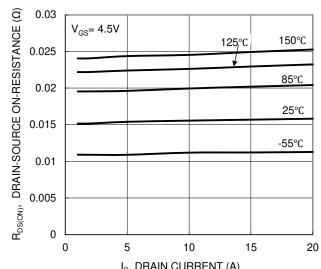
^{9.} Guaranteed by design. Not subject to product testing.







I_D, DRAIN-SOURCE CURRENT (A) Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage



I_D, DRAIN CURRENT (A) Figure 5. Typical On-Resistance vs. Drain Current and Temperature

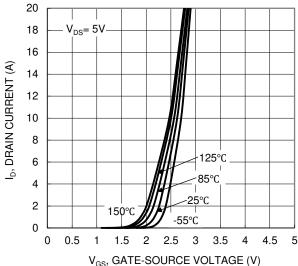


Figure 2. Typical Transfer Characteristic

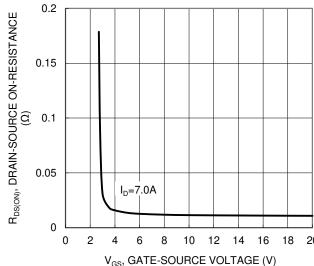


Figure 4. Typical Transfer Characteristic

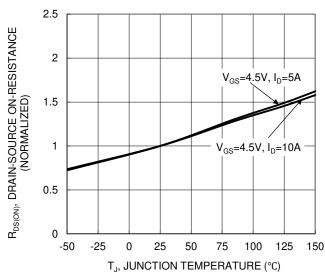


Figure 6. On-Resistance Variation with Temperature

DMN3021LFDF



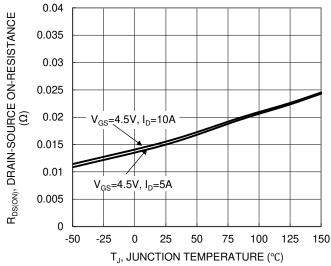
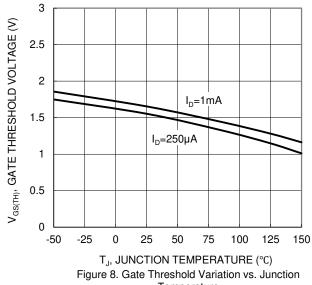
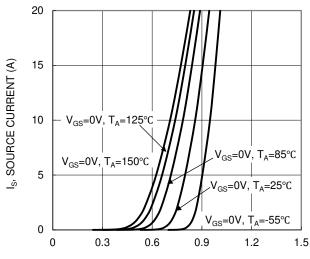


Figure 7. On-Resistance Variation with Temperature



Temperature



V_{SD}, SOURCE-DRAIN VOLTAGE (V) Figure 9. Diode Forward Voltage vs. Current

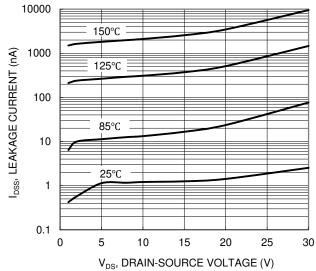
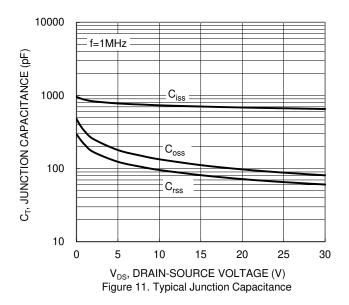
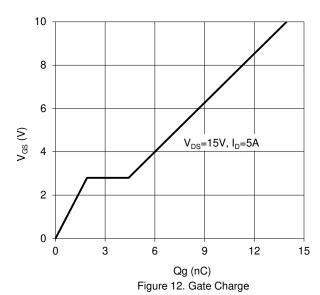
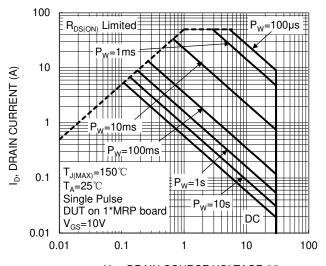


Figure 10. Typical Drain-Source Leakage Current vs. Voltage









 V_{DS} , DRAIN-SOURCE VOLTAGE (V) Figure 13. SOA, Safe Operation Area

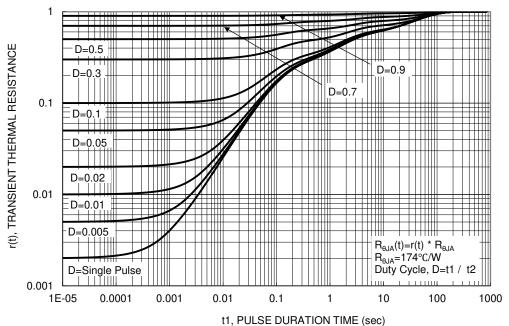


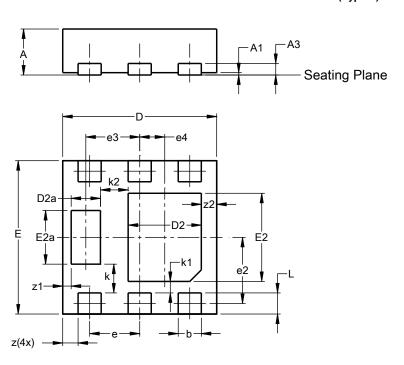
Figure 14. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

U-DFN2020-6 (Type F)

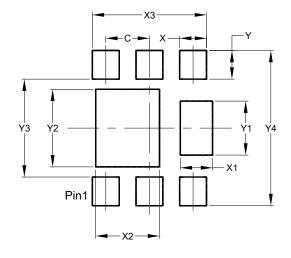


U-DFN2020-6									
(Type F)									
Dim	Min	Min Max Typ							
Α	0.57	0.63	0.60						
A1	0.00	0.05	0.03						
А3	1	-	0.15						
b	0.25	0.35	0.30						
D	1.95	2.05	2.00						
D2	0.85	1.05	0.95						
D2a	0.33	0.43	0.38						
E	1.95	2.05	2.00						
E2	1.05	1.25	1.15						
E2a	0.65	0.70							
е	0.65 BSC								
e2).863 BS	SC						
e3		0.70 BS	С						
e4	0.325 BSC								
k		0.37 BS							
k1	0.15 BSC								
k2	0.36 BSC								
L	0.225 0.325 0.275								
Z	0.20 BSC								
z 1	0.110 BSC								
z2	0.20 BSC								
All Dimensions in mm									

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

U-DFN2020-6 (Type F)



Dimensions	Value
Dilliensions	(in mm)
С	0.650
X	0.400
X1	0.480
X2	0.950
Х3	1.700
Y	0.425
Y1	0.800
Y2	1.150
Y3	1.450
Y4	2.300



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